

Announcement and Call for Abstracts

IMAPS Mid-Atlantic Chapters announce the *Mid-Atlantic Microelectronics Conference*

www.imaps.org/midatlantic

This event will be co-located with IMAPS Portable/Wireless Workshop

June 17-18, 2010
Atlantic City Hilton
Atlantic City, New Jersey - USA

Abstract Deadline: April 5, 2010

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Chapter Organizing Committee: Steve Lehnert (Metro), Erica Folk (Chesapeake), Mike Salloum (Garden State), Benson Chan (Empire), Jim Wood (Keystone) and John Mazurowski (Cleveland Pittsburgh)	

Workshop Focus:

Many IMAPS leaders in the Empire, Metropolitan, Garden State, Keystone, Chesapeake and Cleveland/Pittsburgh chapters invite you to submit an abstract for review for the Mid-Atlantic Microelectronics Packaging Conference.

The Conference will be co-located with two half-day professional development courses and a full-day workshop on Portable Electronics on Thursday, June 17. The Conference will officially begin with an evening reception that night.

The Program Committee seeks papers that demonstrate how products, technologies, and applications are expanding and redefining the microelectronics industry. Presentations in four sessions will be determined based on the following business and industry topics:

Industry

- Biomedical Electronics
- Telecom - Microwave
- Military Electronics
- Consumer Electronics
- Renewable Energy: Fuel Cells, Solar, Wind
- Thermal Management
- Manufacturing, Outsourcing & Quality
- High Performance Interconnects and Boards
- Imaging Sensors
- Nano-Technologies
- Opto-electronics
- Market Analysis and Drivers

Advanced Processes & Materials

- 3D and High Density Packaging
- Photonic/ Optoelectronic packaging
- LED Packaging
- MEMS and Nano Packaging
- Underfill/ Encapsulants and Adhesives
- Green packaging / Compliance with RoHS
- Flip-Chips
- Wirebonding and Stud Bumping
- Embedded and Integrated Passives
- Ceramic, Polymer and Conductive Materials
- Cu/ Low-K

Those wishing to present a paper at the Mid-Atlantic Microelectronics Conference must submit a 200-300 word abstract electronically **no later than April 5, 2010**, using the on-line submittal form at: www.imaps.org/abstracts.htm. Full written papers are not required; however, an extended abstract of 1-4 pages is due for accepted presenters no later than May 28, 2010.

The Microelectronics Foundation sponsors Student Paper Competitions in conjunction with all Advanced Technology Workshops (ATWs) and Conferences. Students submitting their work and identifying that "**Yes, I'm a full-time student**" on the abstract submission form; will automatically be considered for these competitions. The review committee will evaluate all student papers/posters and award at least one student author with a \$1,000 check at the ATW/Conference. The selected student must attend the event to present his or her work and receive the award. The Foundation will return the registration fee for the winner. The winner must pay for travel and lodging expenses.

Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 202-548-4001 if you have questions.

Accepted papers may be considered for publication in the IMAPS *Journal of Microelectronics and Electronic Packaging*. **All Speakers are required to pay a reduced registration fee and are required to attend the entire event.**

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